

Description

The CM170N10GP is the N-Channel enhancement mode power field effect transistors with high cell density, high voltage planar technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

Features

- V_{DS} : 100V
- I_D (@ $V_{GS}=10V$): 211A
- $R_{DS(ON)}$ (@ $V_{GS}=10V$): < 3.9m Ω
- High density cell design for extremely low $R_{DS(ON)}$
- Excellent on-resistance and DC current capability

Applications

- AC/DC load switch
- SMPS
- Notebooks and Handhelds adapter
- UPS Power

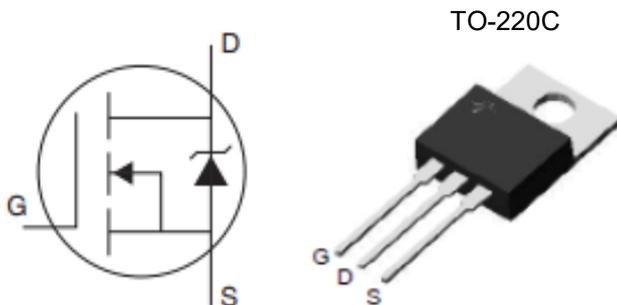
Marking Information



Marking Code = CM170N10GP

Date Code = XXXX

Equivalent Circuit and Pin Configuration



Ordering Information

P/N	Package Type	Packaging
CM170N10GP	TO-220C	Tube

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	100	V
Gate-source Voltage	V_{GS}	± 20	V
Continuous Drain Current ⁽¹⁾	I_D	$T_c=25^\circ\text{C}$ (Silicon Limit)	211
		$T_c=25^\circ\text{C}$ (Package Limit)	120
		$T_c=100^\circ\text{C}$ (Silicon Limit)	116
Pulsed Drain Current ⁽²⁾	I_{DM}	480	A
Total Power Dissipation ⁽³⁾	$PD @ T_c=25^\circ\text{C}$	416	W
	Derating Factor above 25°C	2.78	W/ $^\circ\text{C}$
Single Puls Avalanche Energy ⁽⁴⁾	E_{AS}	540	mJ
Thermal Resistance Junction-to-Case ⁽³⁾	$R_{\theta JC}$	0.63	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (T_c=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =250μA	100			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V, T _C =25°C			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0		4.0	V
Static Drain-Source on-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =30A		3.0	3.9	mΩ
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				211	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, f=100KHz		9050		pF
Output Capacitance	C _{oss}			1300		
Reverse Transfer Capacitance	C _{rss}			20		
Switching Parameters						
Total Gate Charge	Q _g	V _{DS} =50V, I _D =20A, V _{GS} =10V		126		nC
Gate Source Charge	Q _{gs}			38		
Gate Drain Charge	Q _{gd}			22		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =50V, I _D =20A, R _G =2Ω		44		ns
Turn-on Rise Time	t _r			20		
Turn-off Delay Time	t _{D(off)}			102		
Turn-off Fall Time	t _f			23		

Noted: (1) Pulse Test: Pulse Width ≤ 300μs, Duty cycle ≤ 2%.

(2) Pulse width limited by maximum junction temperature.

(3) Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. With 2oz Copper, t ≤ 10s.

(4) E_{AS} is tested at starting T_j = 25°C, L=0.5mH, I_{AS}=46.5A, V_{GS}=10V.

Typical Performance Characteristics

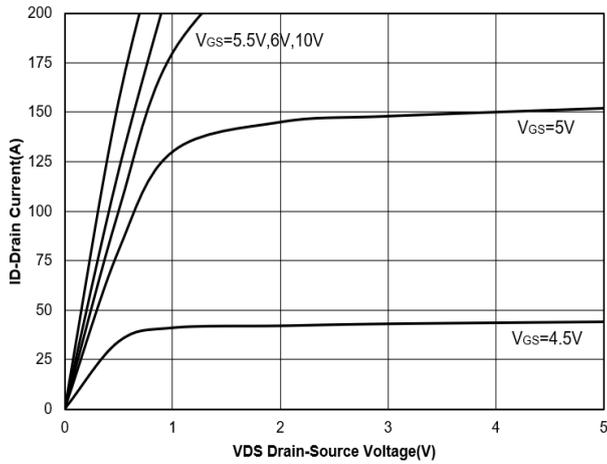


Figure 1. Output Characteristics

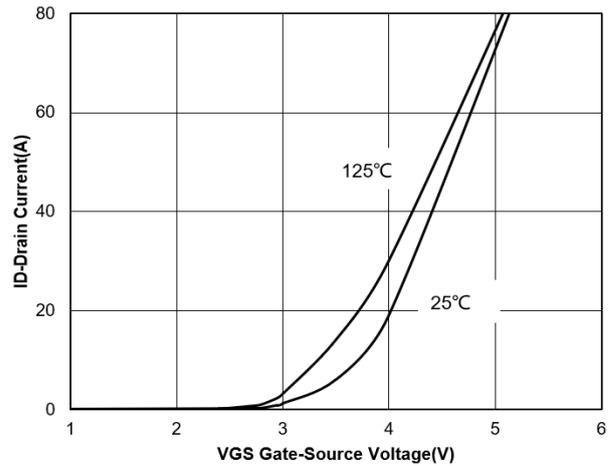


Figure 2. Transfer Characteristics

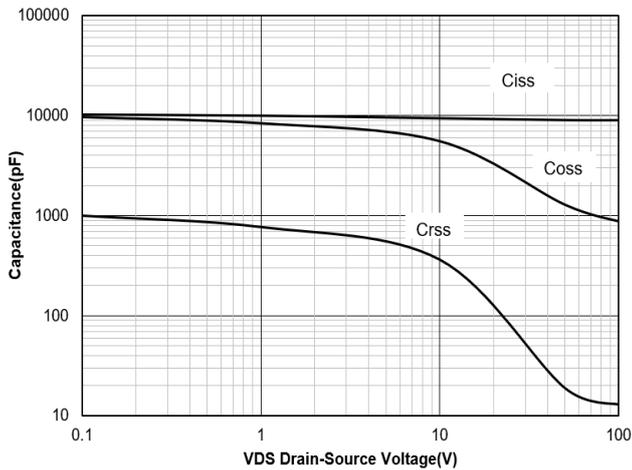


Figure 3. Capacitance Characteristics

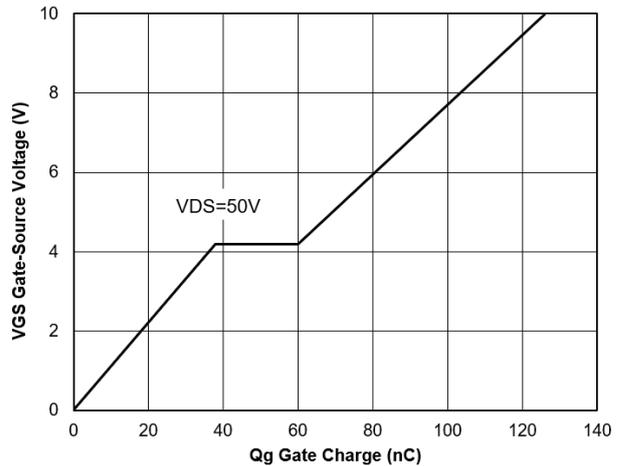


Figure 4. Gate Charge

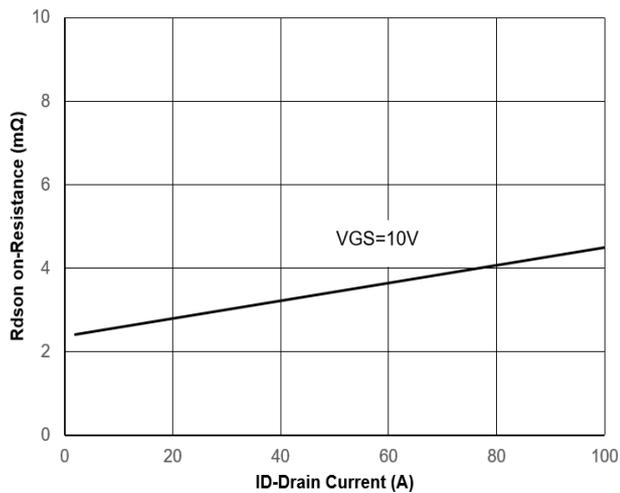


Figure 5. Drain-Source on Resistance

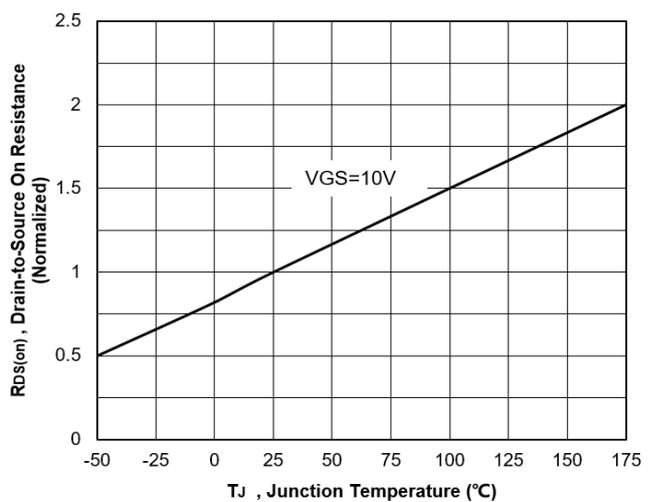


Figure 6. Normalized On-Resistance Vs. Temperature

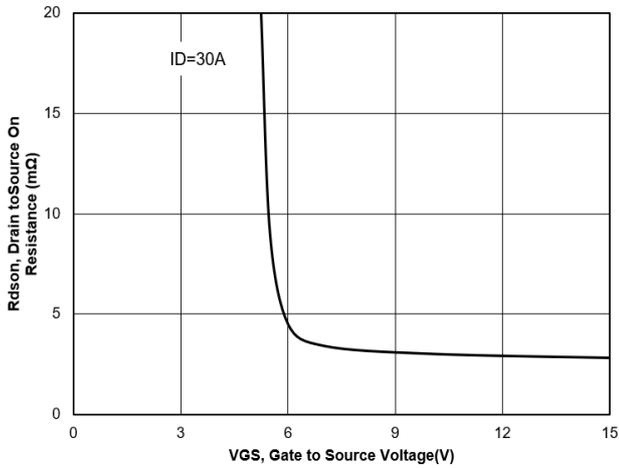


Figure 7. Typical Drain to Source ON Resistance VS Gate Voltage and Drain Current

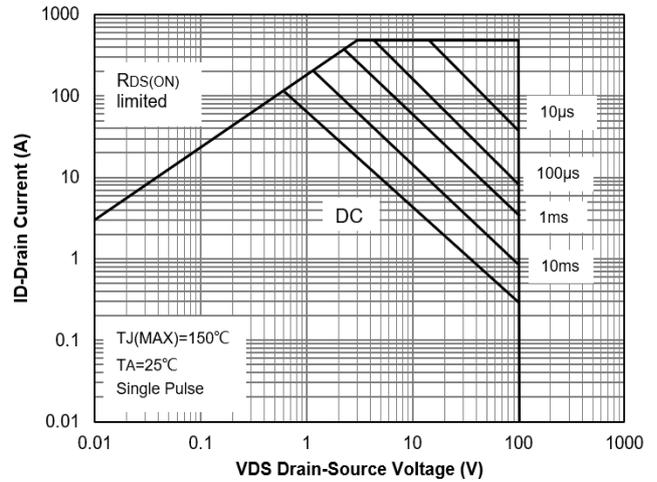


Figure 8. Safe Operation Area

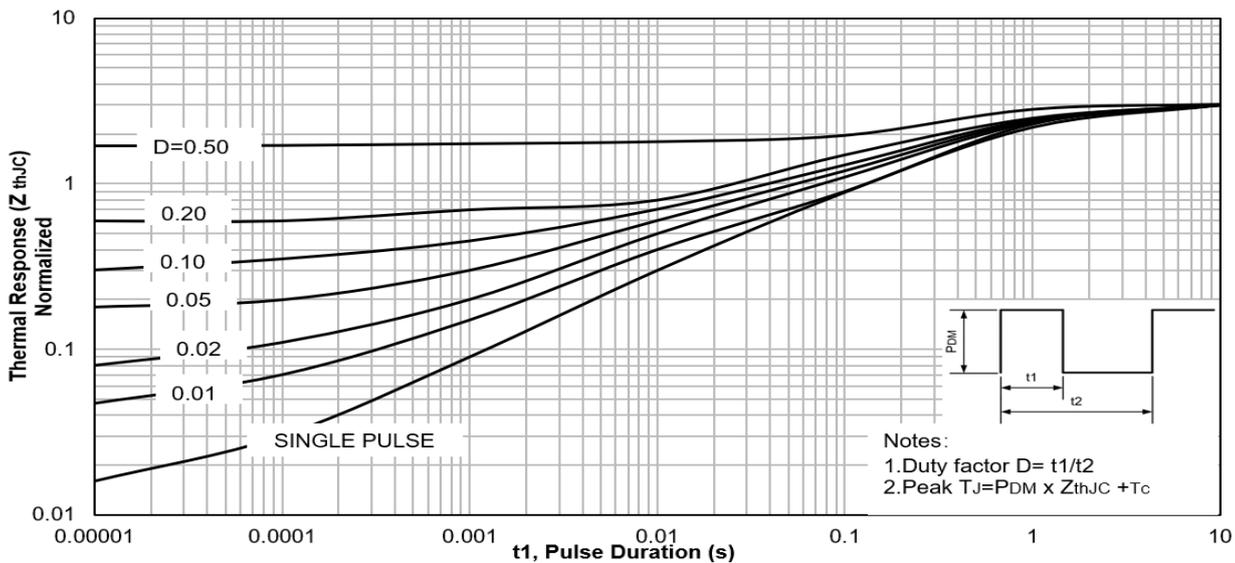


Figure 9. Maximum Effective Transient Thermal Impedance ,Junction-to-Case

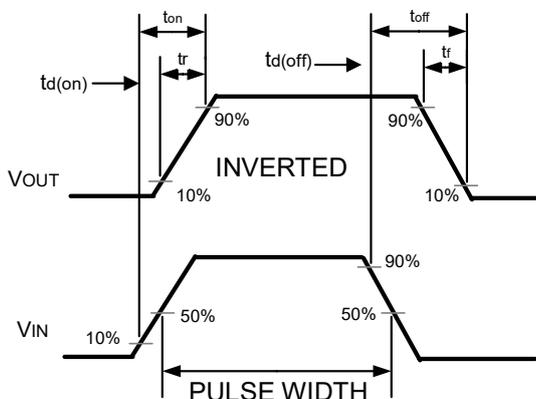


Figure 10. Switching wave

